



Final Product Change Notification

201605004F01

Issue Date: 30-Jun-2016

Effective Date: 14-Oct-2016

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QUALITY

Management Summary

- Expansion of Cu-wire bonding for TSSOP5/6 packages (Phase V)
- Replace Au (gold) wire with Cu (copper) wire in bonding process
- Capacity expansion assembly lines in ATSN

Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

Expansion of Cu-wire bonding for TSSOP5/6 packages (Phase V)

Details of this Change

Introduction of Cu-wire bonding for TSSOP6 and remaining TSSOP5 types in ATSN (NXP Semiconductors Assembly & Test Plant Seremban Malaysia)

- Replace Au (gold) wire with Cu (copper) wire in bonding process

Why do we Implement this Change

- Capacity expansion on state of the art production tools
- Aligning with world technology trends, NXP starts to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties
- Increased environmental friendliness (eco-friendly)

Identification of Affected Products

- The changed products can be identified by backward traceability of their marking date code
- No change in product top side marking

Product Availability

Sample Information

Samples are available upon request

Limited samples are available upon request for high volume types in Logic sample store Nijmegen The

Netherlands

Production

Planned first shipment 14-Oct-2016

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Not applicable

Related Notifications

Notification	Issue Date	Effective Date	Title
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201501001F0112-Sep-2015	25-Dec-2015		Expand assembly production capacity SOT353 package at APM (Assembly Plant Malaysia)
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Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 30-Jul-2016.

Remarks

- See previous Cu-wire bonding introduction for TSSOP5 in PCN 201409013F01 (Cu-wire Phase IV)
- No change in data sheet, form, fit, function, quality or reliability anticipated
- No change in ordering part number / 12NC
- No change in product top side marking

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Emile Busink
Position PCN specialist - QA engineering Logic Products
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